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an interposer having a die attach surface and an external surface opposite of the die attach surface disposed in between the semiconductor die and the at least one external terminal, the interposer having at least one electrically conductive interconnect electrically coupling the at least one bond pad of the semiconductor die positioned adjacent to the die attach surface to the at least external terminal positioned adjacent to the external surface, the interposer being formed of an organic substrate or a polyimide substrate; and

a plurality of strips of compliant adhesive film extending substantially the entire distance between the first pair of opposed lateral edges disposed in between the semiconductor die and the interposer to adhere the semiconductor die to the die attach surface of the interposer, the strips of compliant adhesive film each extending substantially less than the distance between the second pair of opposed lateral edges.

5. (Twice Amended) The package of claim 1 wherein each of the plurality of strips of compliant adhesive film comprises:

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a first adhesive layer adhered to the die attach surface of the interposer;
a second adhesive layer adhered to the semiconductor die; and
at least one compliant carrier layer disposed in between the first and second adhesive layers and to which the first and second adhesive layers are adhered.

6. (Twice Amended) The package of claim 1 wherein each of the plurality of strips of compliant adhesive film comprises a single layer of elastomer material.

7. (Twice Amended) The package of claim 1 wherein the first surface of the semiconductor die is adhered to the die attach surface of the interposer by the plurality of strips of compliant adhesive film.

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9. (Twice Amended) The package of claim 1 wherein the plurality of strips of compliant adhesive film comprise strips of compliant adhesive film positioned in parallel along a longitude of the semiconductor die.

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 10. (Twice Amended) The package of claim 1 wherein a first and a second of the plurality of strips of compliant adhesive film are positioned at a right angle with respect to each other.

Sub F2
 11. (Twice Amended) A device package assembly for a semiconductor die being constructed from a process comprising:
 laminating a plurality of strips of compliant adhesive film to an interposer having at least one electrically conductive interconnect, the interposer being formed of an organic substrate or a polyimide substrate and further having a die attach surface to which the semiconductor die is attached, and an external surface opposite of the die attach surface;
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 attaching to the interposer the semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated, the die having first and second pairs of lateral edges, the strips of compliant adhesive film extending substantially the entire distance between the first pair of opposed lateral edges, the strips each extending substantially less than the distance between the second pair of opposed lateral edges; and
 bonding the at least one electrically conductive interconnect to the at least one electrically conductive bond pad.

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 17. (Twice Amended) *IF* The package assembly of claim 11 wherein each of the plurality of strips of compliant adhesive film comprises a single layer of elastomer material.

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 18. (Twice Amended) The package assembly of claim 11 wherein the plurality of strips of compliant adhesive film comprise strips of film positioned in parallel along a longitude of the semiconductor die.

Sub F3
 38. (Amended) A semiconductor device package, comprising:
 a semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated, the die having first and second pairs of lateral edges;

Sub F3 > an interposer having a die attach surface and at least one electrically conductive interconnect electrically coupled to at least one bond pad of the semiconductor die, the interposer being formed of an organic substrate or a polyimide substrate; and

a plurality of strips of compliant adhesive film extending substantially the entire distance between the first pair of opposed lateral edges between the die attach surface and the semiconductor die to adhere the semiconductor die to the die attach surface of the interposer, the strips of compliant adhesive film each extending substantially less than the distance between the second pair of opposed lateral edges.

39. (Amended) The semiconductor device package of claim 38 wherein the strips of compliant adhesive film comprise an elastomer material.

Sub 18 > 40. (Amended) The semiconductor device package of claim 38 wherein the strips of compliant adhesive film comprise strips of compliant adhesive material positioned in parallel with a longitude of the semiconductor die.

Sub F4 > 42. (Twice Amended) A semiconductor device package, comprising:
a semiconductor die having a first surface on which at least one electrically conductive bond pad is fabricated, the die having first and second pairs of lateral edges;

an interposer having a die attach surface and at least one electrically conductive interconnect electrically coupled to at least one bond pad of the semiconductor die, the interposer being formed of an organic substrate or a polyimide substrate; and

a plurality of strips of compliant adhesive film extending substantially the entire distance between the first pair of opposed lateral edges between the die attach surface and the semiconductor die to adhere the semiconductor die to the die attach surface of the interposer, the strips of compliant adhesive film each extending substantially less than the distance between the second pair of opposed lateral edges.